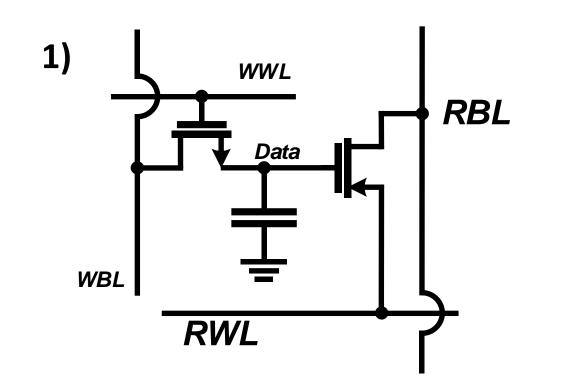


Compute-In-Memory with SAR ADC & 2T1C DRAM for MAC Operations

Giyeol Kim, Minkyu Song and Soo Youn Kim

Department of Semiconductor Science, Dongguk University, Seoul, Korea

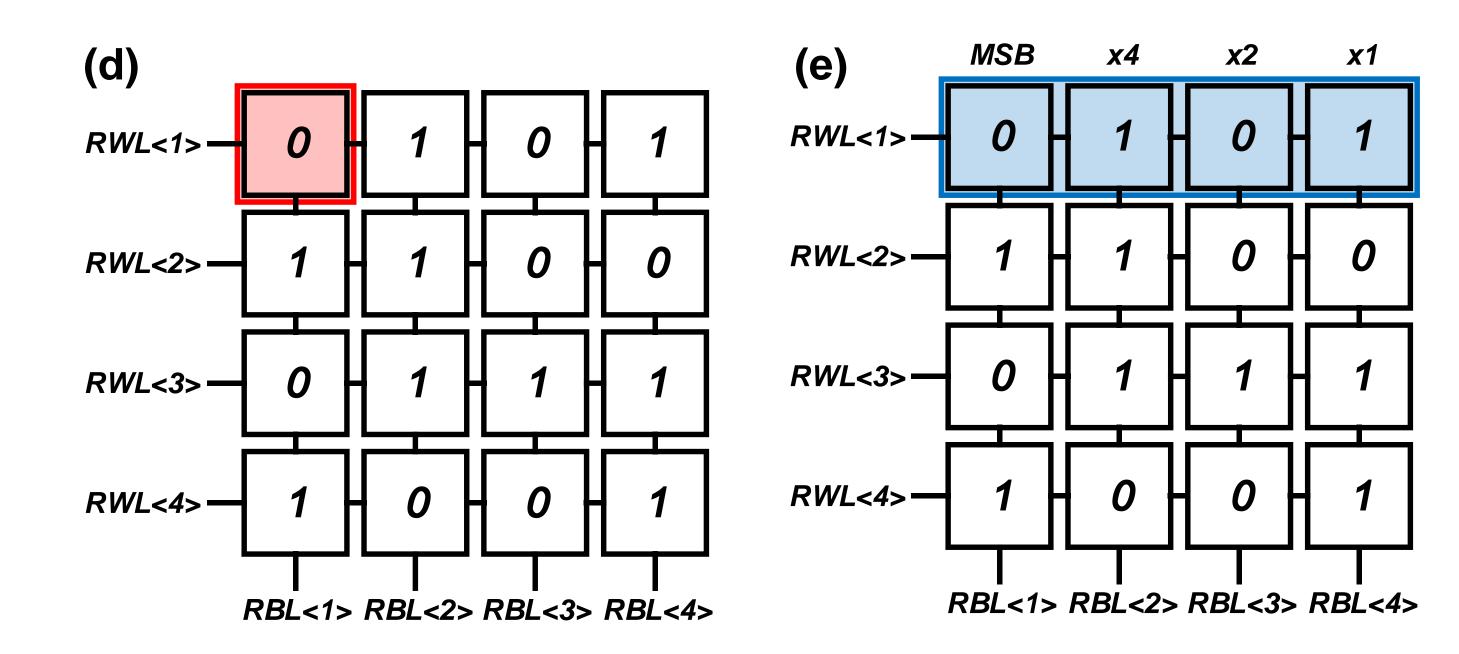
Introduction



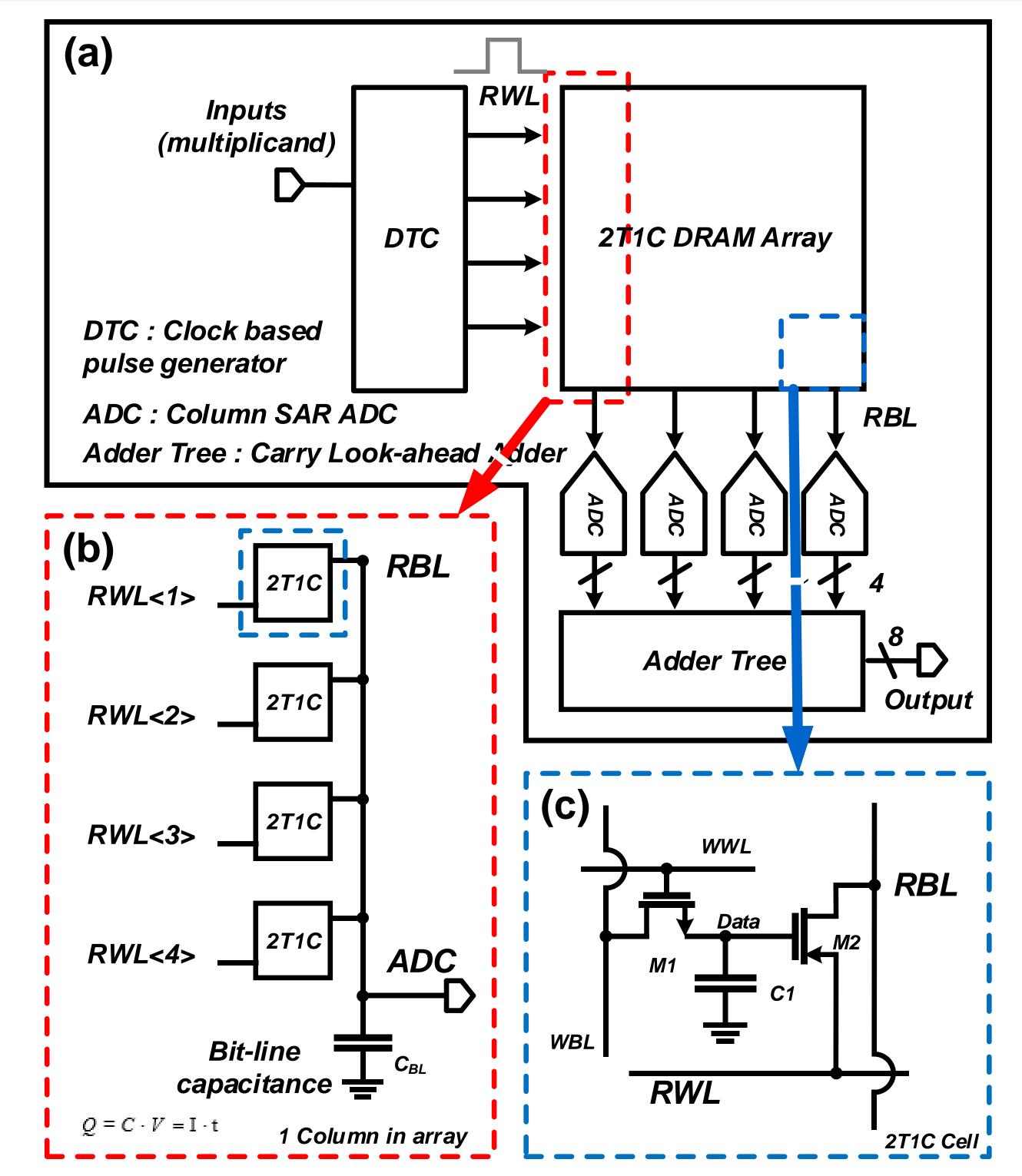
1): 2T1C DRAM cell using NMOS as access MOS, and PMOS as readout MOS

- In 2T1C DRAM, data can be read non- \bullet destructive through read-word-line (RWL) & read-bit-line (RBL).
- Since the format of data is current of ulletreadout MOS, charge is stacked in RBL as time goes.
- We proposed multiplication & summation in \bullet memory using particular time pulse to RWL, and saturation current of readout MOS in saturation condition.

Additional Bit-line Digit Weight



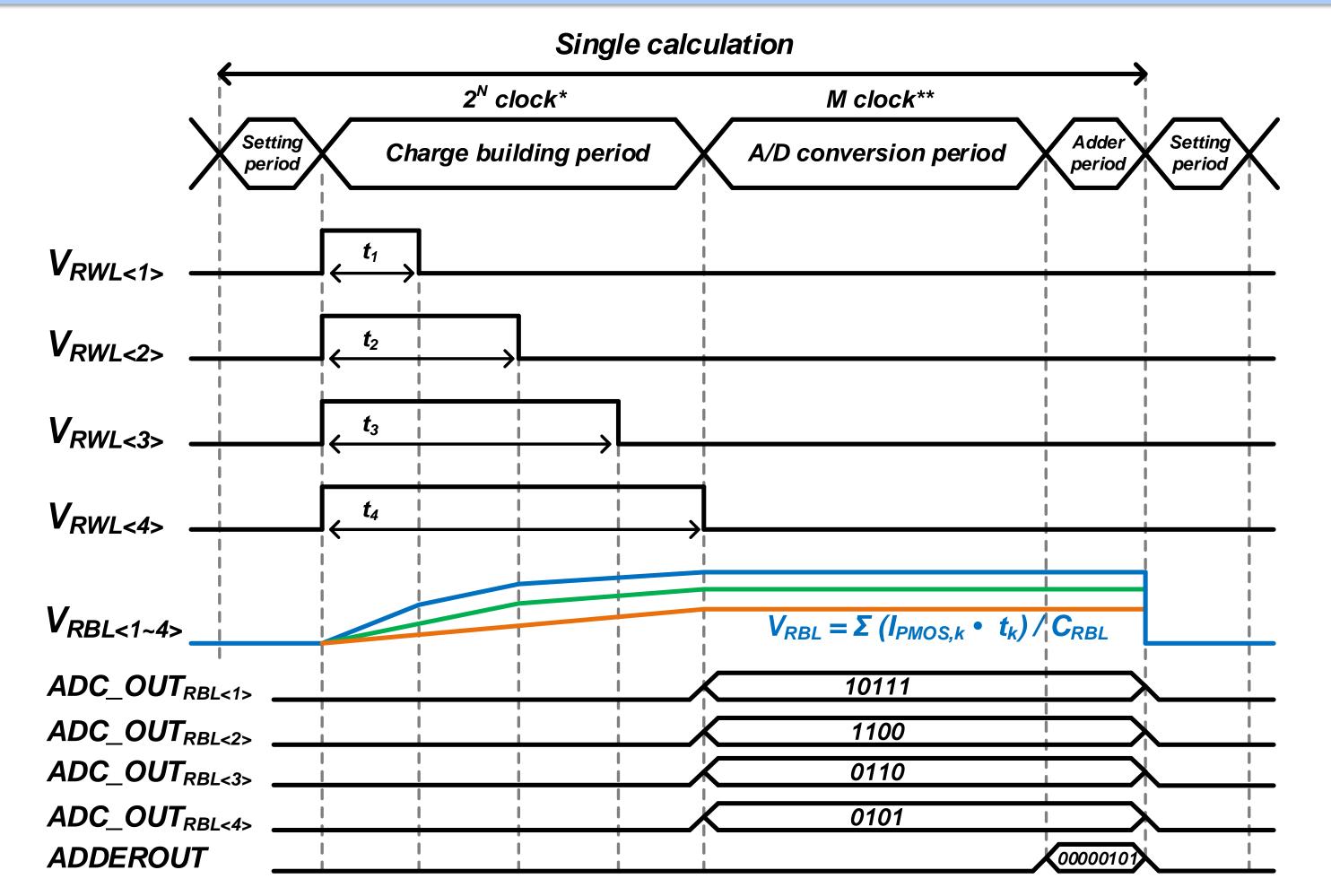
Proposed CIM Circuit & System



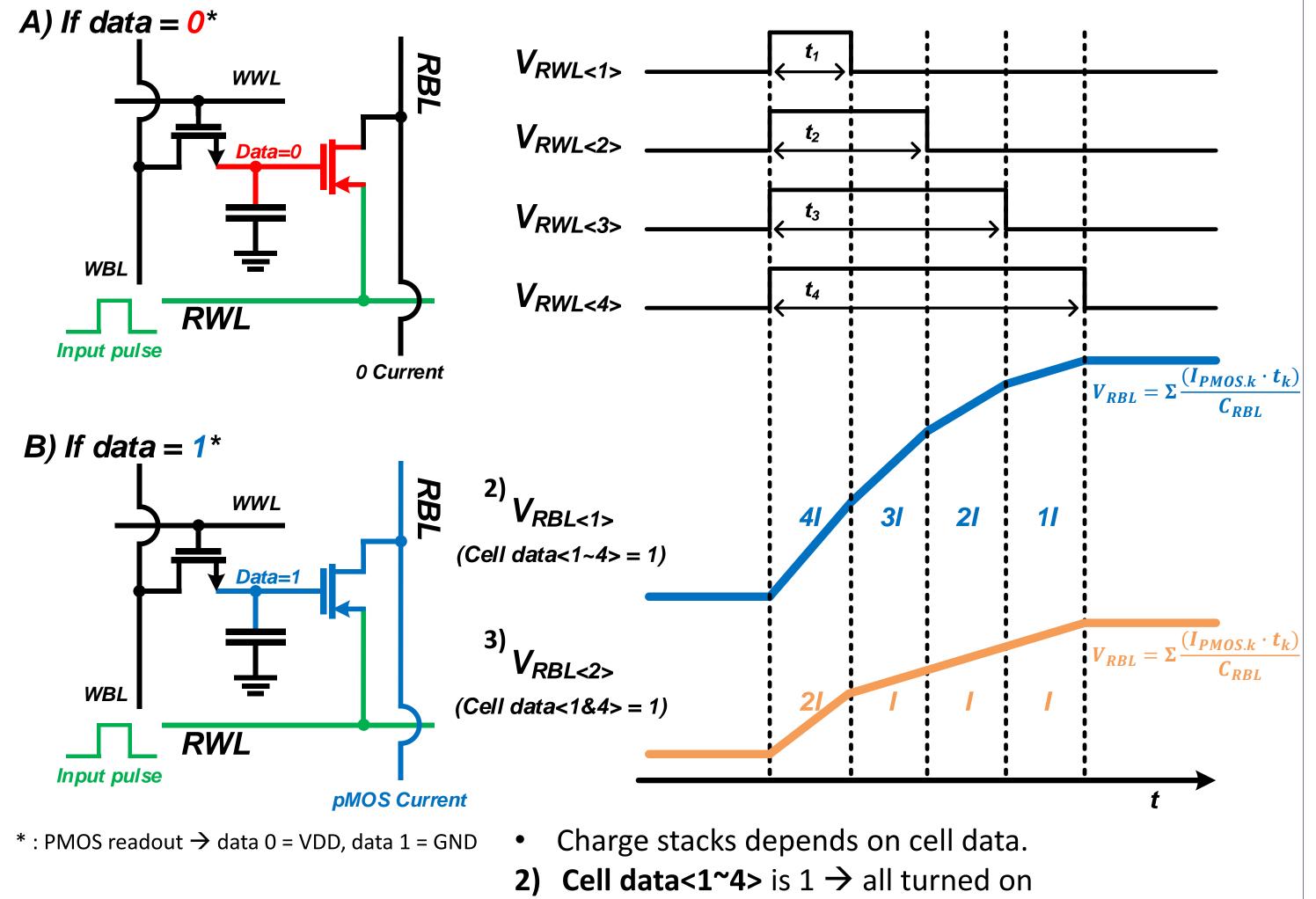
(d) : Calculation is proceeds in column parallel. Therefore, cell data can be only 1-bit (0 & 1). (e) : To achieve multi-bit cell data, Weigh the digits in each column from (x1) to (MSB).

- Multiplication & summation is done in each RBL.
- Results in each column contains additional digit weight data. •
- Using digital adder tree to finish digit calculation at final step of total operation as shown • in diagram (a).

Simulation Results



- a) Overall structure of CIM DTC unit converts input bits into clock-based pulse width signal, signal goes through read-word-line of 2T1C cell. After charge stacking, using ADC to get column calculation data.
- **b) 1** Read-bit-line column schematic in array Input signal goes through readout MOS(M2), current came out depends on cell data, and stacking charge at bitline capacitance in parallel.
- c) 2T1C DRAM cell
- Read-Bit-Line Charge Stacking Operation



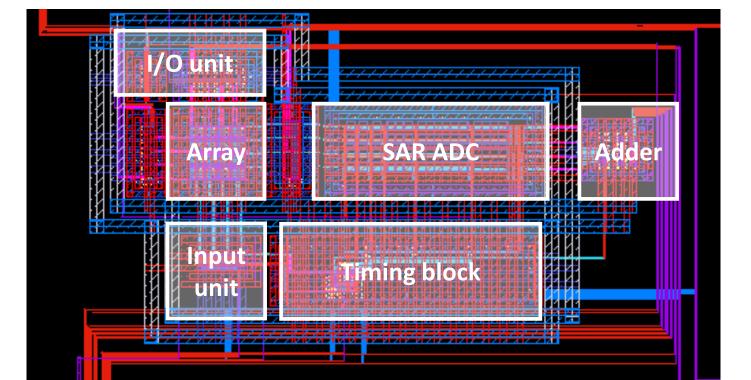
3) Cell data<1&4> is $1 \rightarrow$ only cell 1, 4 is turned on

* : N = # of input bit, ** : M = # of ADC bit

- As pulse width of RWL signals are different, and so are the data in cells, amount of stacked charge in column is different.
- Using SAR ADC to convert each V_{RBL} into digital code (*ADC_OUT*), then adder tree finishes digit calculation (*ADDEROUT*).

Chip Layout and Summary (Test in progress)

Full Chip Layout



Process Tech.	1poly-7metal 28nm CMOS
Memory Size	16-bit
Bit Cell Area	10um x 10um (100um²)
# of Input	2-bit x4
# of Weight	4-bit x4
Output	8-bit x1
Chip Size	400um x 200um (0.08mm ²)
Power Domain	1 V (Digital)
System CLK Frequency	100MHz
MAC Calculation Time	14 clock
SAR ADC Resolution	4-bit
Power Consumption	7.2 μW/single multiplication



Dongguk University, System IC Design Lab.